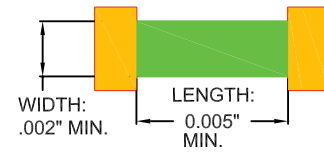


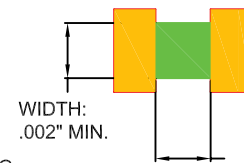
# CONDUCTORS & RESISTORS - VALUES & TOLERANCES

LAYER TO LAYER REGISTRATION:  $\pm 0.0005$ "

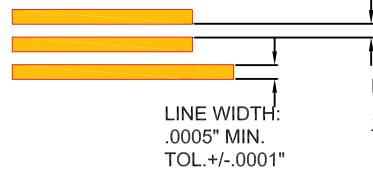
(VALUE TO:  $\pm 0.1\%$ )



(VALUE TO:  $\pm 5\%$ )



$.005$ " MIN. LATERAL RESISTOR SPACING



HALF VIA EDGE WRAP:

$.005$ " MIN.  
MIN. DIA. GREATER OF SUBSTRATE THICKNESS OR  $.010$ "

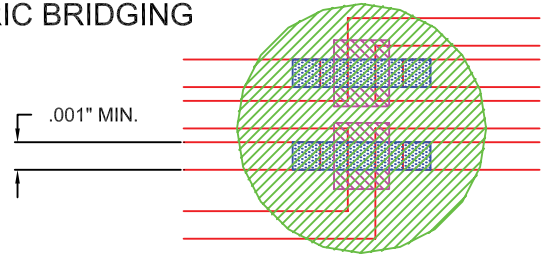
METAL PULLBACK

$0.003$ " PREFERRED

$.007$ "  $\pm 0.003$ " INTRUSION  
 $.006$ : TYP. RADIUS  
 $.020$ " TYP. WIDTH

SLOTTED VIA EDGE WRAP

## DIELECTRIC BRIDGING

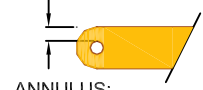
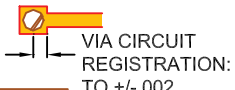


## HOLES AND MACHINED FEATURES

CIRCUIT FEATURE LOCATION TOL.:

$\pm 0.002$ " RELATIVE TO CIRCUIT DATUM

TOLERANCE TO  $\pm 0.003$ "



BACK PATTERN

CUTOUT

$.020$ " MIN.

RADIUS:  $.006$ " MIN.

FRONT TO BACK PATTERN REGISTRATION:  $\pm 0.002$

LASER CUT FEATURES:  $\pm 0.003$ "

GREATER OF  $.020$ " OR HOLE DIA.

SPACING:  $.020$ " MIN.

HOLE DIA.:  
 $.007$ " MIN. PLATED  
 $.007$ " MIN. FILLED  
 $0.6$  MIN. DIA. TO SUBSTRATE THICKNESS  
THRU DIA.  $\pm 0.003$ "  
SURFACE DIA. TO  $\pm 0.001$ "